

## N and P-Channel Enhancement Mode Power MOSFET

### Description

The NCE4606 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### General Features

- **N-Channel**

$V_{DS} = 30V, I_D = 6.5A$

$R_{DS(ON)} < 24m\Omega @ V_{GS}=10V$

$R_{DS(ON)} < 37m\Omega @ V_{GS}=4.5V$

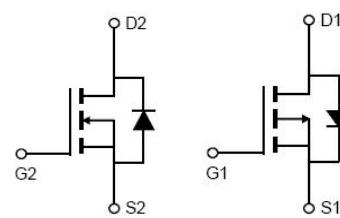
- **P-Channel**

$V_{DS} = -30V, I_D = -7A$

$R_{DS(ON)} < 32m\Omega @ V_{GS}=-10V$

$R_{DS(ON)} < 70m\Omega @ V_{GS}=-4.5V$

- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- MSL3 up to 260°C peak reflow

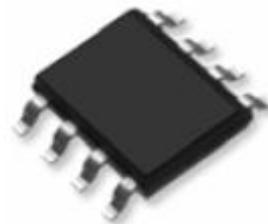


N-channel      P-channel

Schematic diagram



Marking and pin assignment



SOP-8 top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE4606	NCE4606	SOP-8	Ø330mm	12mm	4000 units

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		$V_{DS}$	30	-30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current $T_A=25^\circ C$		$I_D$	6.5	-7	A
	$T_A=70^\circ C$		5.4	-5.8	
Pulsed Drain Current (Note 1)		$I_{DM}$	30	-30	A
Maximum Power Dissipation	$T_A=25^\circ C$	$P_D$	2.0	2.0	W
Single pulse avalanche energy (Note 6)		$E_{AS}$	39	72	mJ
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 To 150	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	62.5	°C/W
Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	P-Ch	62.5	°C/W

**N-CH Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	33	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.6	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=6\text{A}$	$T_J=25^\circ\text{C}$	-	19	24
			$T_J=125^\circ\text{C}$	-	30	39
			$T_J=150^\circ\text{C}$	-	34	44
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$	$T_J=25^\circ\text{C}$	-	26	37
			$T_J=125^\circ\text{C}$	-	41	58
			$T_J=150^\circ\text{C}$	-	45.5	64
Gate resistance	$R_G$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	1.1	-	$\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=6\text{A}$	15	-	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	530.3	-	PF
Output Capacitance	$C_{\text{oss}}$		-	67.1	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	61.2	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=6\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$	-	4.5	-	nS
Turn-on Rise Time	$t_r$		-	2.5	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	14.5	-	nS
Turn-Off Fall Time	$t_f$		-	3.5	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$	-	14.2	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	1.8	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	3.3	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=6\text{A}$	-	0.8	1.2	V
Diode Forward Current (Note 2)	$I_{\text{S}}$		-	-	6.5	A
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = 25^\circ\text{C}, I_F = I_S$ $dI/dt = 100\text{A}/\mu\text{s}$ (Note 3)	-	10	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	5	-	nC

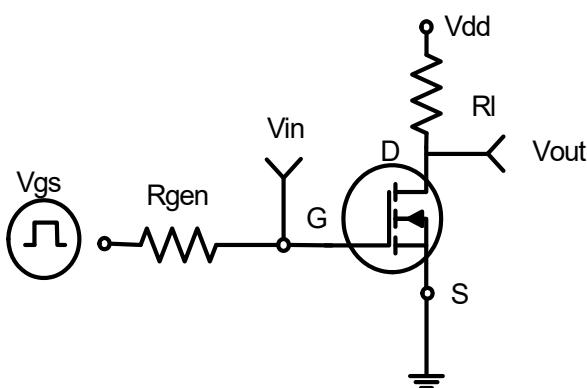
**P-CH Electrical Characteristics ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-33	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	-1.65	-2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-6.5A$	$T_J=25^\circ C$	-	28	32
			$T_J=125^\circ C$	-	41	48
			$T_J=150^\circ C$	-	45	52
		$V_{GS}=-4.5V, I_D=-6.5A$	$T_J=25^\circ C$	-	49	70
			$T_J=125^\circ C$	-	63	89
			$T_J=150^\circ C$	-	67.5	96
Gate resistance	$R_G$	$V_{DS}=0V, V_{GS}=0V, F=1.0MHz$	-	4.2	-	$\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-5V, I_D=-6.5A$	10	-	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V, F=1.0MHz$	-	729.4	-	PF
Output Capacitance	$C_{oss}$		-	112.6	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	107.5	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, I_D=-6.5A$ $V_{GS}=-10V, R_{GEN}=6\Omega$	-	7.5	-	nS
Turn-on Rise Time	$t_r$		-	5.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	19	-	nS
Turn-Off Fall Time	$t_f$		-	7	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-15V, I_D=-6.5A$ $V_{GS}=-10V$	-	16.6	-	nC
Gate-Source Charge	$Q_{gs}$		-	1.8	-	nC
Gate-Drain Charge	$Q_{gd}$		-	4.2	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_s=-6.5A$	-	-	-1.2	V
Diode Forward Current (Note 2)	$I_s$		-	-	-7	A
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ C, I_F = I_s$ $di/dt = 100A/\mu s$ (Note 3)	-	15	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	10	-	nC

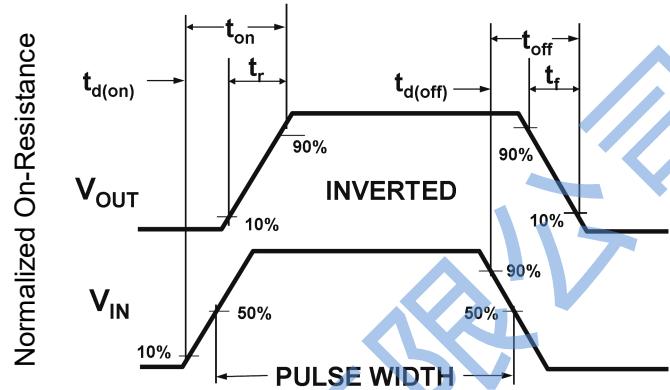
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

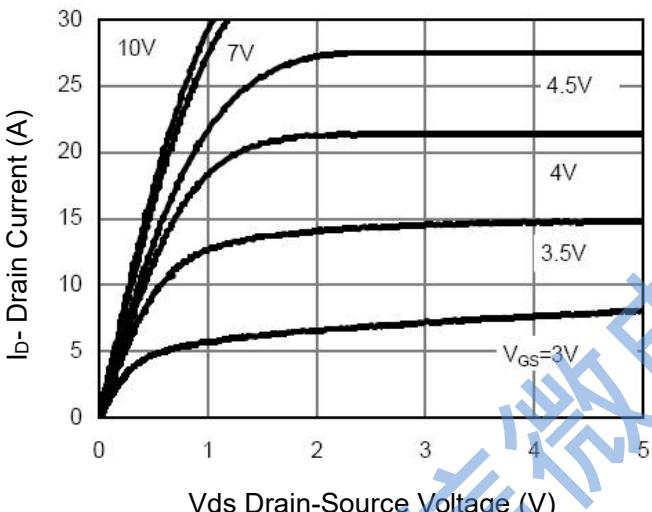
### N- Channel Typical Electrical and Thermal Characteristics (Curves)



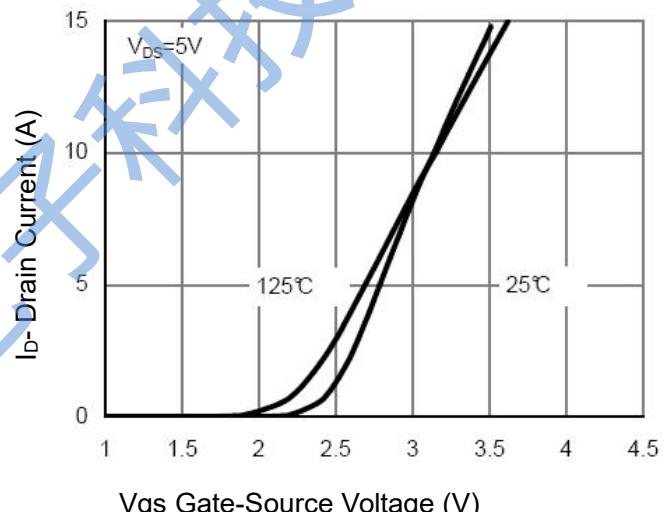
**Figure 1:Switching Test Circuit**



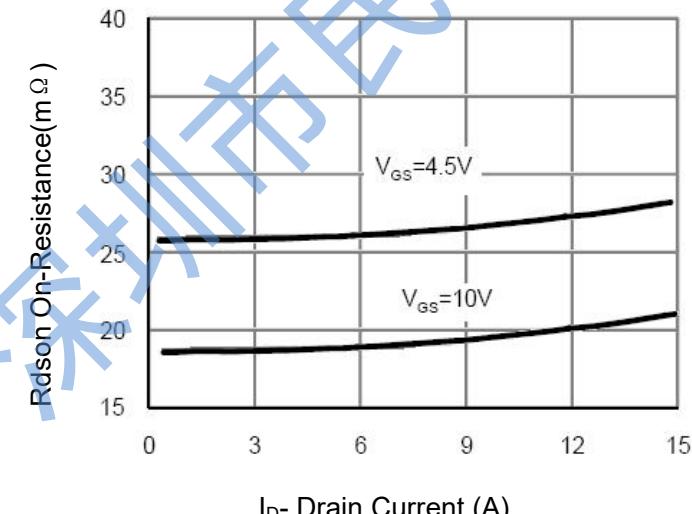
**Figure 2:Switching Waveforms**



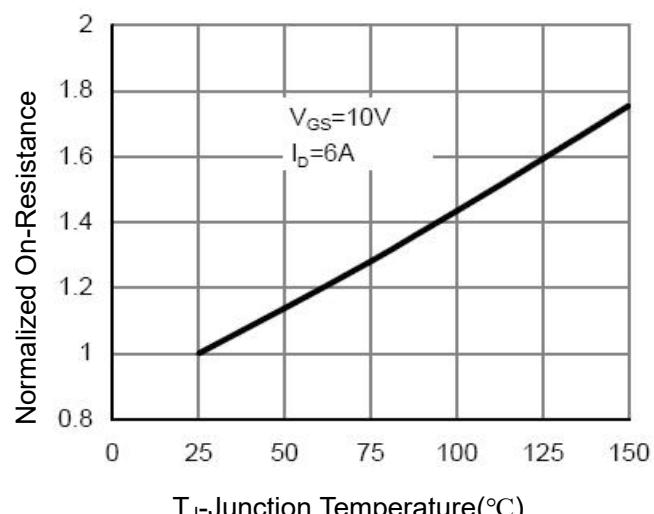
**Figure 3 Output Characteristics**



**Figure 4 Transfer Characteristics**



**Figure 5 Drain-Source On-Resistance**



**Figure 6 Drain-Source On-Resistance**

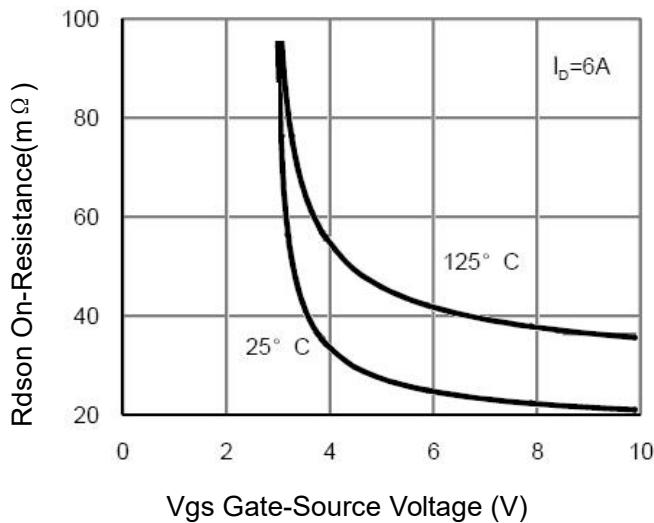


Figure 7  $R_{DS(on)}$  vs  $V_{GS}$

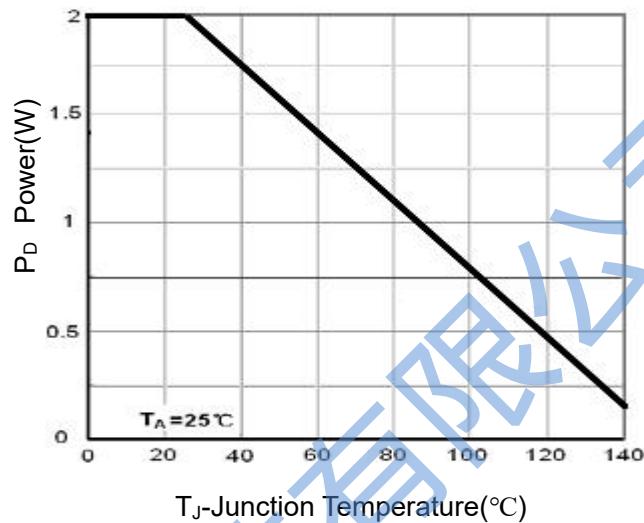


Figure 8 Power Dissipation

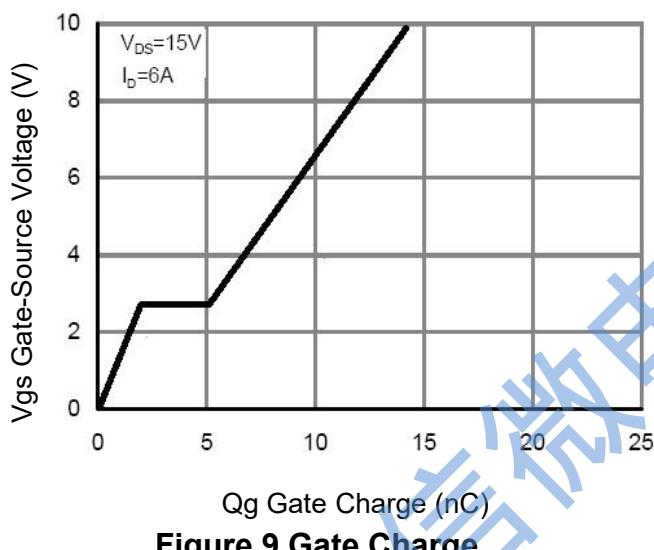


Figure 9 Gate Charge

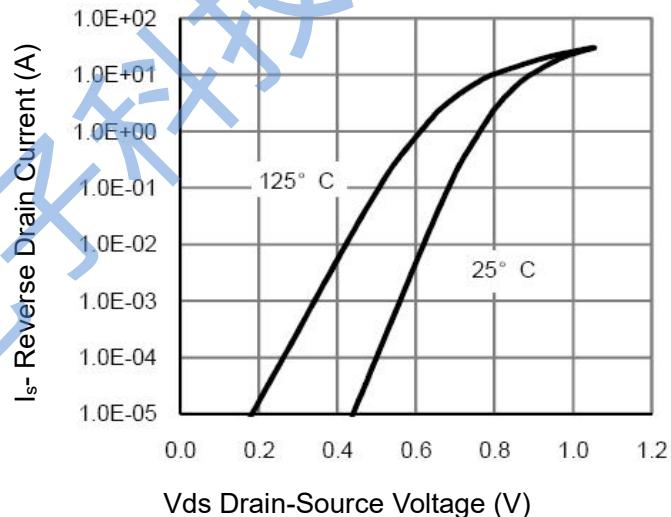


Figure 10 Source-Drain Diode Forward

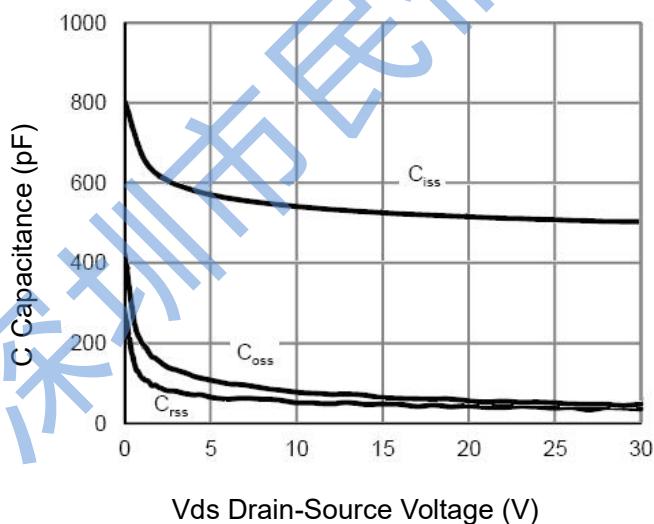


Figure 11 Capacitance vs  $V_{DS}$

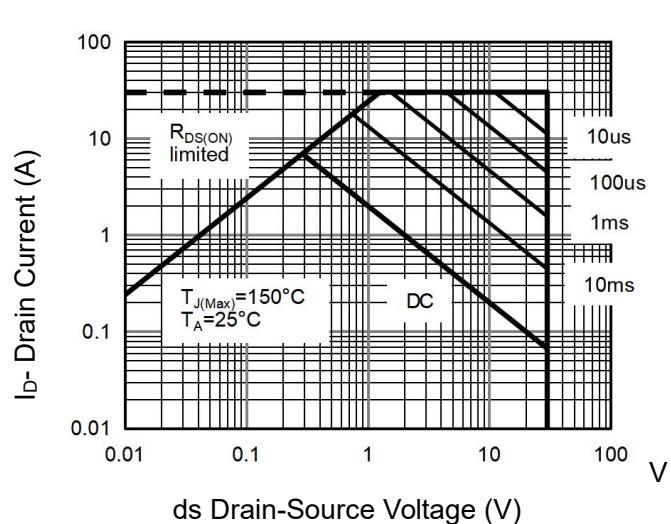
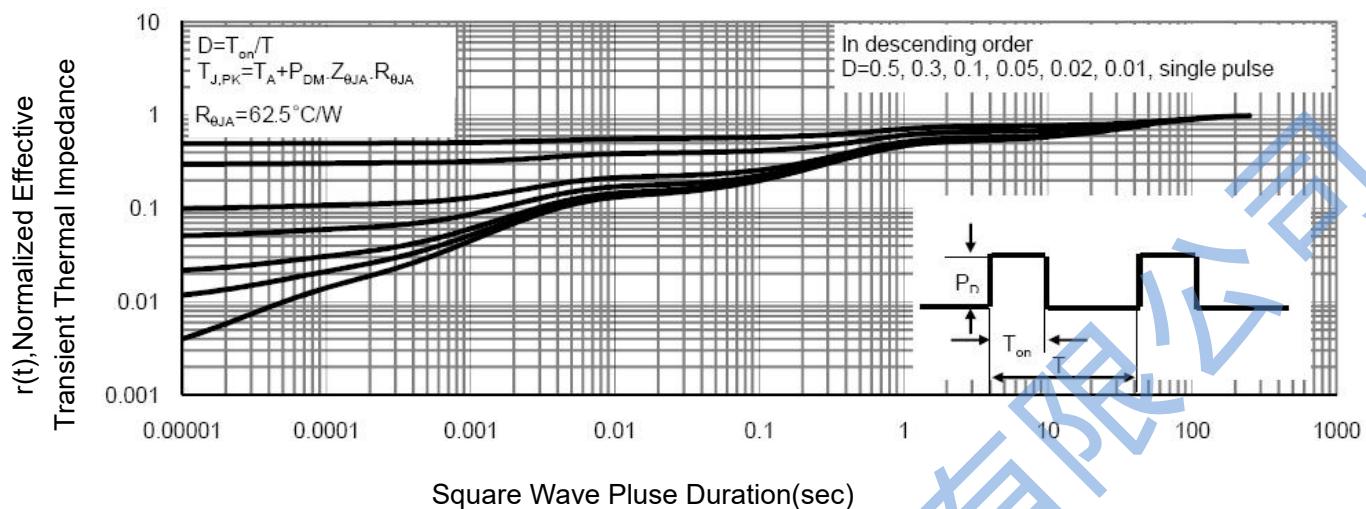
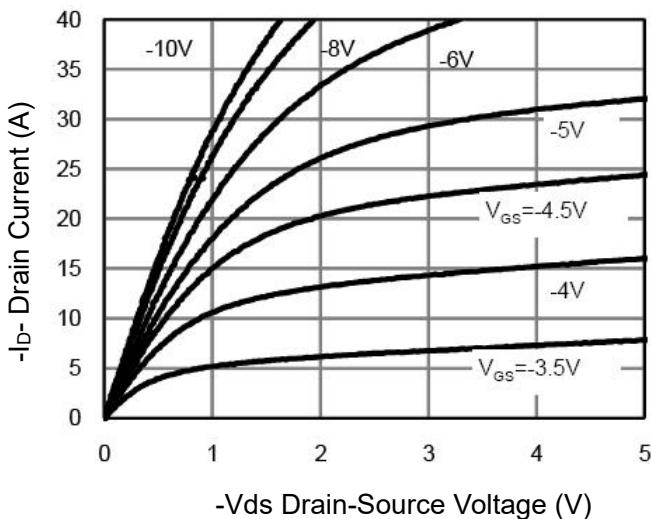


Figure 12 Safe Operation Area

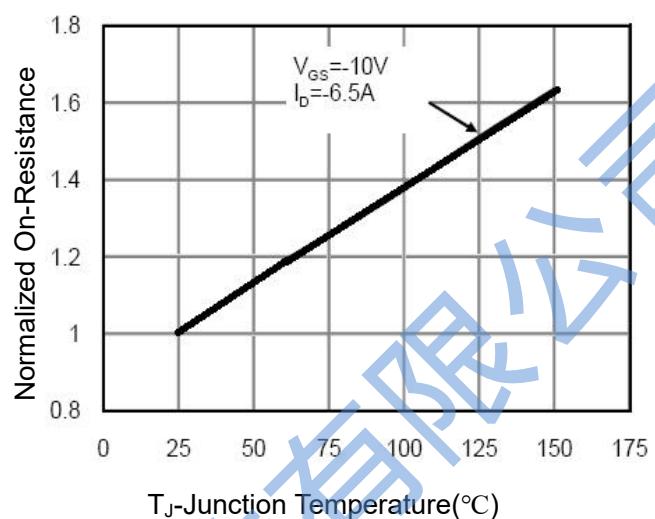


**Figure 13 Normalized Maximum Transient Thermal Impedance**

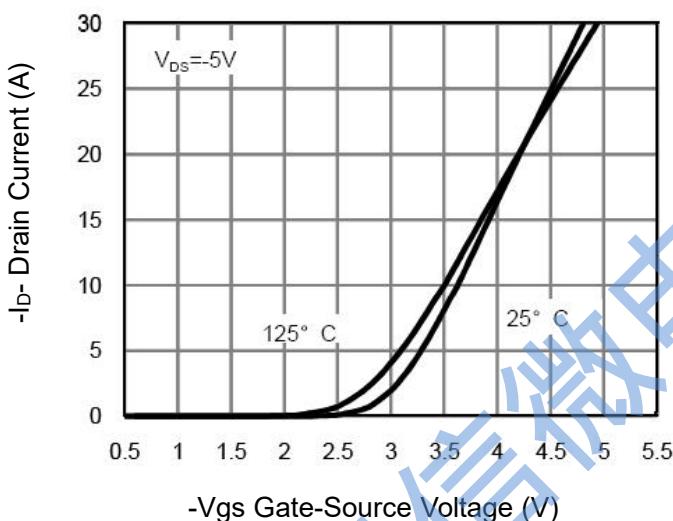
### P- Channel Typical Electrical and Thermal Characteristics (Curves)



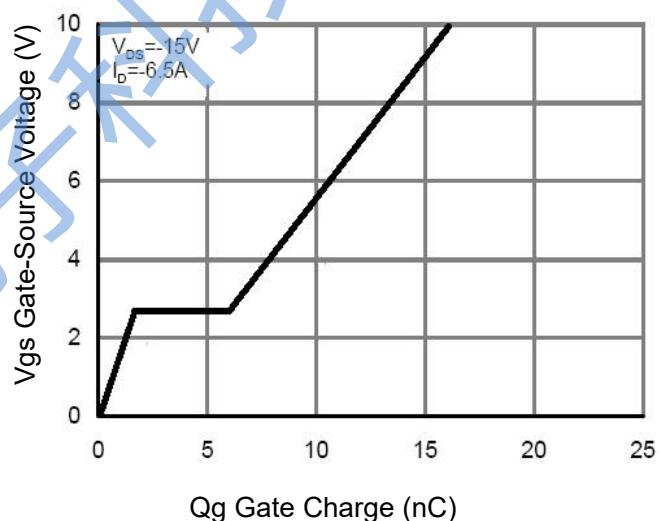
**Figure 1 Output Characteristics**



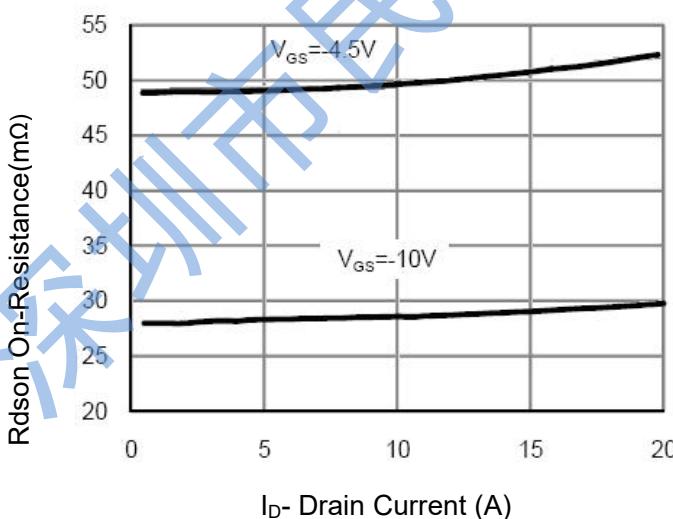
**Figure 4 Rdson-Junction Temperature**



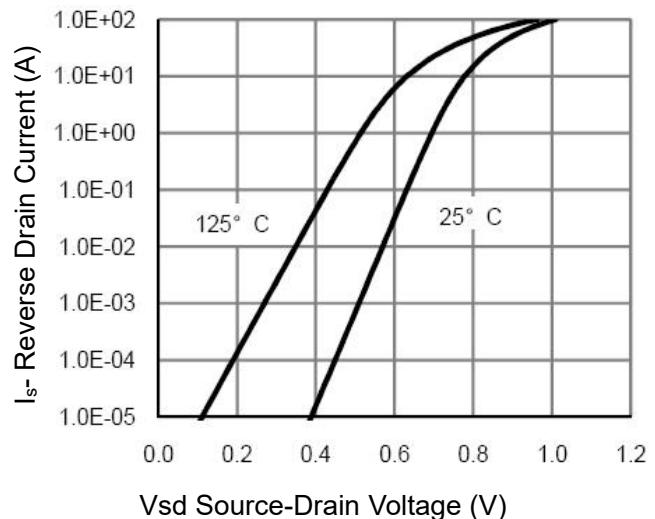
**Figure 2 Transfer Characteristics**



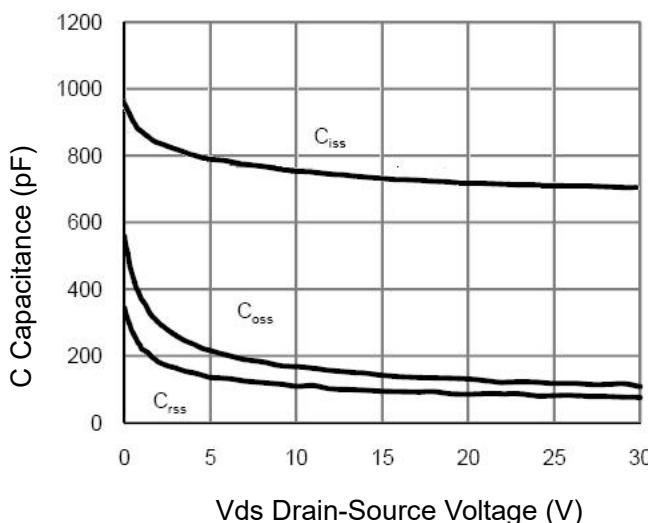
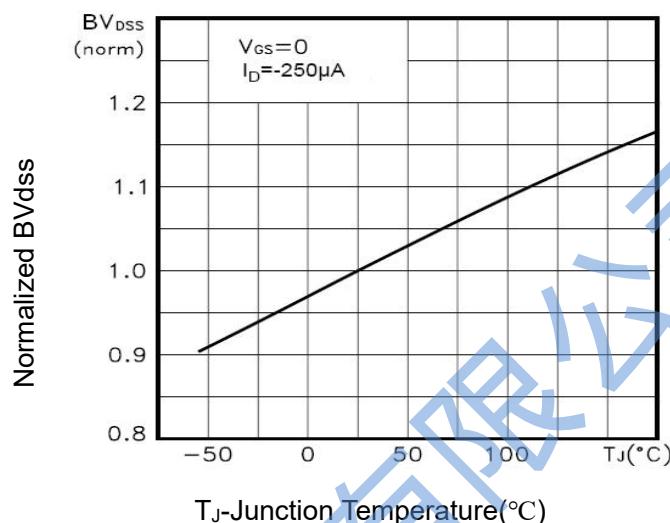
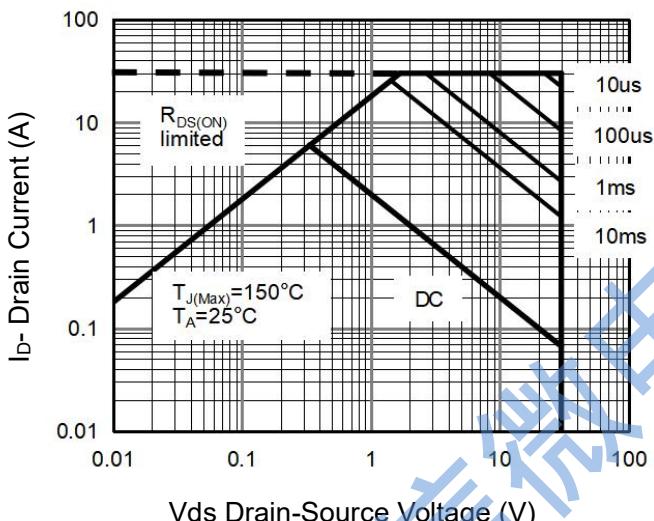
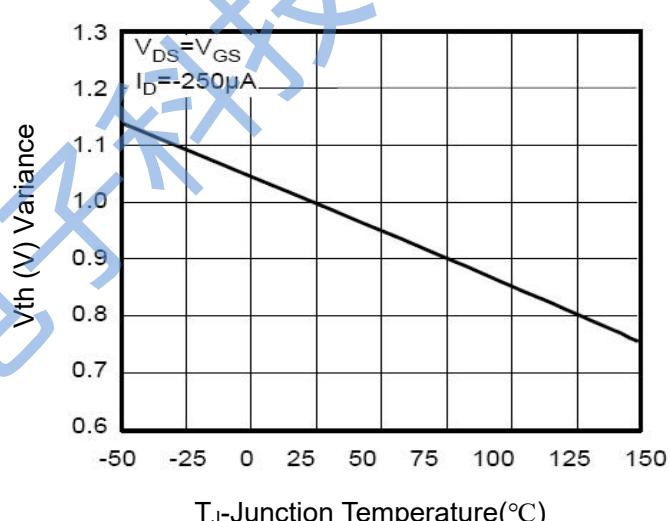
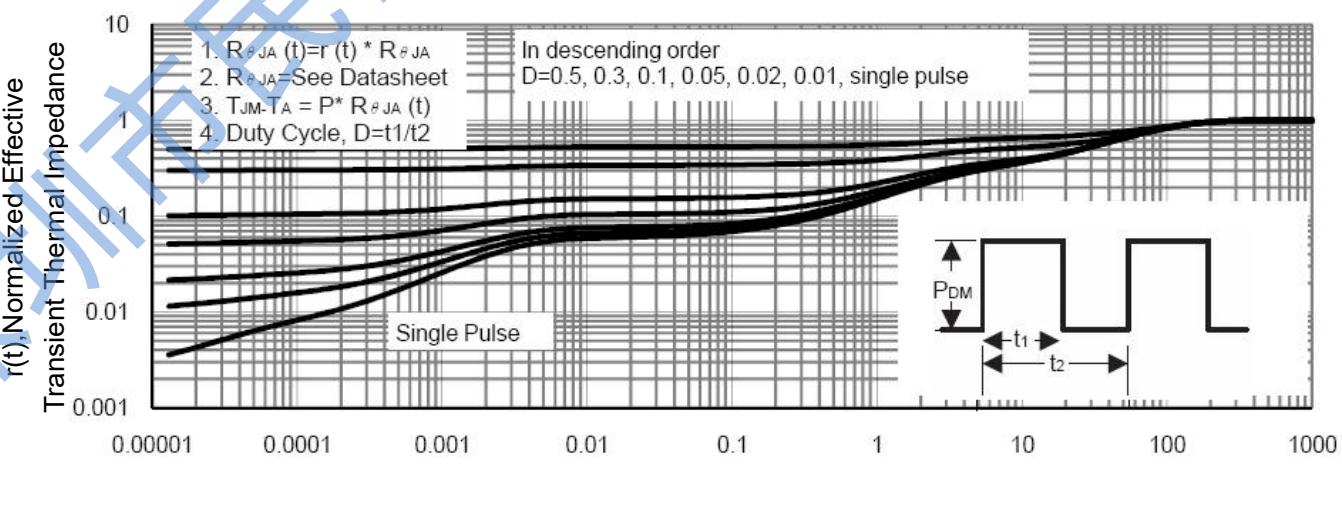
**Figure 5 Gate Charge**

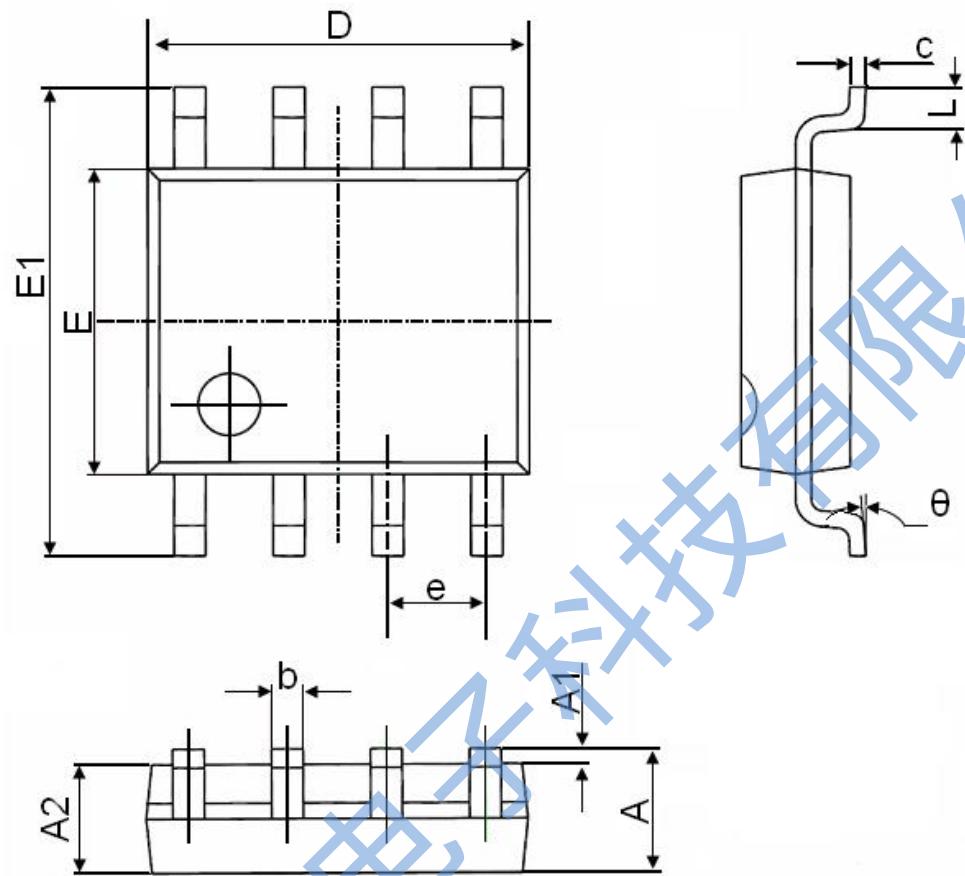


**Figure 3 Rdson- Drain Current**



**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9  $BV_{dss}$  vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10  $V_{GS(th)}$  vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

**SOP-8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



## Attention

- Any and all NCE power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE power representative nearest you before using any NCE power products described or contained herein in such applications.
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